



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C101GCANNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100pF, 100V, ±2%, C0G, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>101</u> <u>G</u> <u>C</u> <u>A</u> <u>N</u> <u>N</u> <u>N</u> <u>O</u> <u>C</u> (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11)

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0805 (inch code)) L: 2.0	± 0.1 mm	W:	1.25 ± 0.1	mm
(3)	Dielectric	C0G	(8)	Inner electrode		Ni	
4	Capacitance	100 pF	•	Termination		Cu	
⑤	Capacitance	±2 %		Plating		Sn 100%	(Pb Free)
	tolerance		9	Product		Normal	
6	Rated Voltage	100 V	10	Special		Reserved for	future use
7	Thickness	0.65 ± 0.1 mr	m 11	Packaging		Cardboard Ty	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition			
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms			
Q	1000 min				
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	200% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	COG				
Characterisitcs	(From -55 $^{\circ}\!$				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change :	Bending to the limit (1mm)			
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120°C for 10~30sec.)			
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	within ±2.5% or ±0.25pF whichever is larger				
	Tan δ, IR : initial spec.				

	Performance	Test condition			
Vibration Test	Capacitance change :	Amplitude : 1.5mm			
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)			
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)			
Moisture	Capacitance change :	With rated voltage			
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs			
	Q: 200 min				
	IR: 500Mohm or 25Mohm $\cdot \mu$ F				
	Whichever is Smaller				
High Temperature	Capacitance change :	With 200% of the rated voltage			
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature			
	Q: 350 min	1000+48/-0hrs			
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F				
	Whichever is Smaller				
Temperature	Capacitance change :	1 cycle condition			
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25°C			
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$ C			
		5 cycle test			

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.